TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π −MOS V)

2SK4002

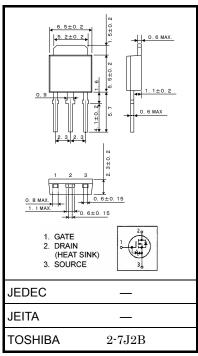
Chopper Regulator, DC/DC Converter and Motor Drive Applications

Unit: mm

• Low drain–source ON-resistance : R_{DS} (ON) = 4.2 Ω (typ.) • High forward transfer admittance : $|Y_{fS}|$ = 1.7 S (typ.) • Low leakage current : I_{DSS} = 100 μ A (max) (V_{DS} = 600 V) • Enhancement mode : V_{th} = 2.0~4.0 V (V_{DS} = 10 V, I_{D} = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Charac	cteristic	Symbol	Rating	Unit
Drain-source volta	ge	V_{DSS}	600	V
Drain-gate voltage	$(R_{GS} = 20 \text{ k}\Omega)$	V_{DGR}	600	V
Gate-source voltage	ge	V_{GSS}	±30	V
Drain current	DC (Note 1)	I _D	2	Α
	Pulse (t = 1 ms) (Note 1)	I _{DP}	5	Α
	Pulse (t = 100 µs) (Note 1)	I _{DP}	8	Α
Drain power dissipa	ation (Tc = 25°C)	P _D	20	W
Single-pulse avalanche energy (Note 2)		E _{AS}	93	mJ
Avalanche current		I _{AR}	2	Α
Repetitive avalanch	ne energy (Note 3)	E _{AR}	2	mJ
Channel temperatu	ire	T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C



Weight: 0.36 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	6.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 41 mH, R_G = 25 Ω , I_{AR} = 2 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



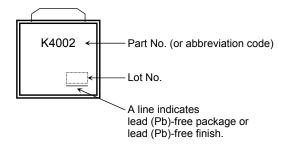
Electrical Characteristics (Ta = 25°C)

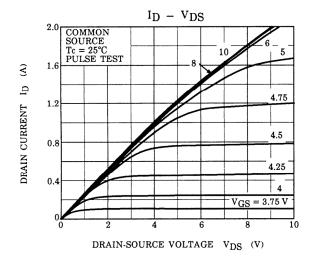
Charac	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	$I_G = \pm 10 \mu A, V_{DS} = 0 V$	±30	_	_	V
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 1 A	_	4.2	5.0	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1 A	8.0	1.7	_	S
Input capacitano	e	C _{iss}		_	380	_	
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		40	_	pF
Output capacitance		Coss		_	120	_	
Switching time	Rise time	t _r	V_{GS} V_{OUT} V_{OUT} V_{DD} V_{DD}	_	15	_	
	Turn-on time	t _{on}		_	25	_	ne
	Fall time	t _f		_	20	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu \text{s}$	_	80	_	
Total gate charg plus gate-drain)	, •		_	9	_		
Gate-source charge		Q _{gs}	$V_{DD} \approx 480 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$		5	_	nC
Gate-drain ("Miller") charge		Q _{gd}			4	_	

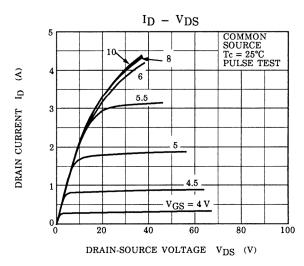
Source-Drain Ratings and Characteristics (Ta = 25°C)

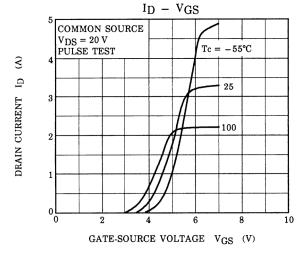
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	2	Α
Pulse drain reverse current (Note 1)	I _{DRP}	t = 1 ms	_	_	5	Α
	I _{DRP}	t = 100 μs	_	_	8	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 2 A, V _{GS} = 0 V	-	_	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 2 A, V _{GS} = 0 V	_	1000	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs		3.5	_	μC

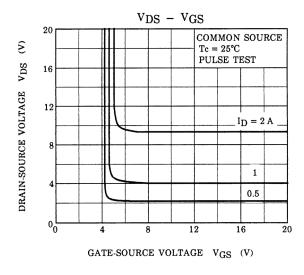
Marking

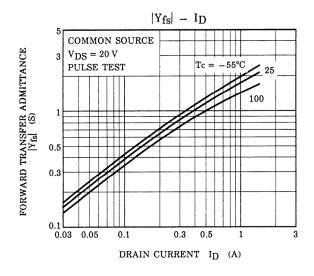


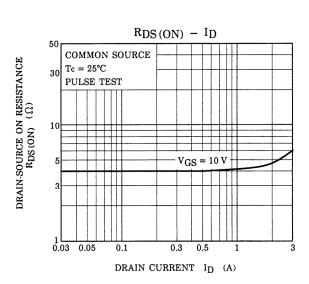




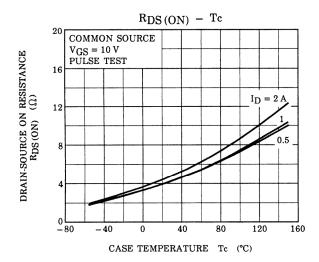


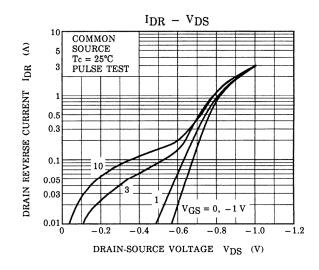


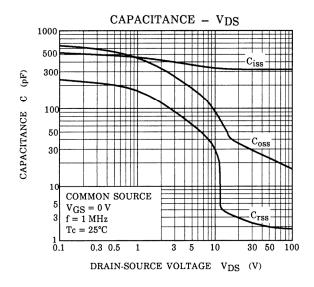


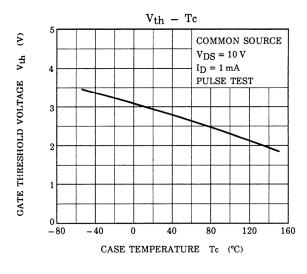


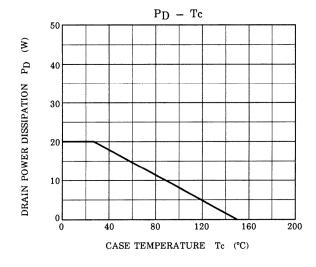
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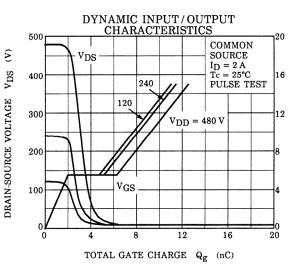




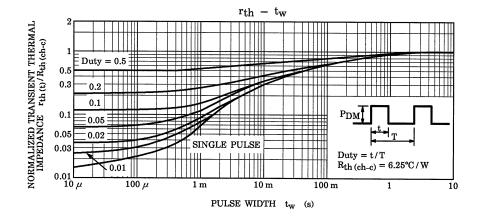


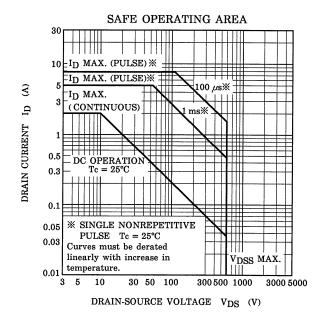


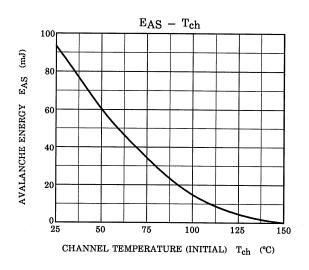


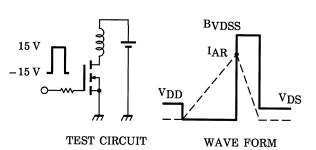


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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V, L} = 41 \text{ mH}$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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20070701-EN

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